

Dae-Suk Kim

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/11620527/publications.pdf>

Version: 2024-02-01

13
papers

217
citations

1478505

6
h-index

1474206

9
g-index

13
all docs

13
docs citations

13
times ranked

364
citing authors

#	ARTICLE	IF	CITATIONS
1	Additive treatment effect of TiO ₂ as supports for Pt-based electrocatalysts on oxygen reduction reaction activity. <i>Electrochimica Acta</i> , 2010, 55, 3628-3633.	5.2	81
2	Strong Interaction between Pt and Thiolated Carbon for Electrocatalytic Durability Enhancement. <i>ACS Catalysis</i> , 2013, 3, 3067-3074.	11.2	34
3	Effect of junction temperature on heat dissipation of high power light emitting diodes. <i>Journal of Applied Physics</i> , 2016, 119, .	2.5	23
4	Moisture Ingress, Behavior, and Prediction Inside Semiconductor Packaging: A Review. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2017, 139, .	1.8	21
5	Method for predicting junction temperature distribution in a high-power laser diode bar. <i>Applied Optics</i> , 2016, 55, 7487.	2.1	16
6	Temperature dependence of morphology and oxygen reduction reaction activity for carbon-supported Pd-Co electrocatalysts. <i>Journal of Applied Electrochemistry</i> , 2010, 40, 1917-1923.	2.9	14
7	Thermal deformation analysis of automotive electronic control units subjected to passive and active thermal conditions. , 2015, , .		6
8	Fine Structure Effect of PdCo electrocatalyst for Oxygen Reduction Reaction Activity: Based on X-ray Absorption Spectroscopy Studies with Synchrotron Beam. <i>Journal of Electrochemical Science and Technology</i> , 2010, 1, 31-38.	2.2	6
9	Direct covalent thiolation of carbon nanotube supports to enhance the durability of highly loaded Pt electrocatalysts. <i>Electrochemistry Communications</i> , 2012, 19, 85-89.	4.7	5
10	Electronic control package model calibration using moiré interferometry. , 2014, , .		5
11	Characterization of Die-Attach Thermal Interface of High-Power Light-Emitting Diodes: An Inverse Approach. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2015, 5, 1635-1643.	2.5	4
12	Hybrid Approach to Conduct Failure Prognostics of Automotive Electronic Control Unit. , 2017, , .		2
13	Inverse approach to characterize die-attach thermal interface of light emitting diodes. , 2016, , .		0